ABSTRACT OF THE DISCLOSURE

LEAD FRAME FOR LOC

A lead frame for LOC is provided which can reduce a variation in coverage of an insulating adhesive, permitting the fixation of a semiconductor chip and wire bonding to be stably performed. In a lead frame for LOC 10 wherein an insulating adhesive for fixing a semiconductor chip is applied to inner leads 11 in their semiconductor chip mounting region, a coverage regulating lead 14 is provided outside the semiconductor chip mounting region and adjacent to inner leads 11a, 11b located at the end of the semiconductor chip mounting region, permitting the insulting adhesive to be homogeneously applied to each of the inner leads 11 without creating any variation in coverage of the adhesive.

This Sheet Has Been Replaced

